

SN74AUP1T157

SCES807 - APRIL 2010

LOW POWER, 1.8/2.5/3.3-V INPUT, 3.3-V CMOS OUTPUT, SINGLE 2-INPUT SCHMITT-TRIGGER BUFFER MULTIPLEXER (NONINVERTED)

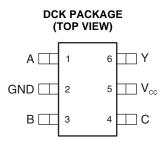
Check for Samples: SN74AUP1T157

FEATURES

- Single-Supply Voltage Translator
- Output Level Up to Supply V_{CC} CMOS Level
 - 1.8 V to 3.3 V (at V_{CC} = 3.3 V)
 - 2.5 V to 3.3 V (at V_{CC} = 3.3 V)
 - 1.8 V to 2.5 V (at V_{CC} = 2.5 V)
 - 3.3 V to 2.5 V (at V_{CC} = 2.5 V
- Schmitt-Trigger Inputs Reject Input Noise and Provide Better Output Signal Integrity
- I_{off} Supports Partial Power Down (V_{CC} = 0 V)
- Very Low Static Power Consumption: 0.1 μA
- Very Low Dynamic Power Consumption: 0.9 μA
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- Pb-Free Packages Available: SC-70 (DCK) 2 x 2.1 x 0.65 mm (Height 1.1 mm)

DESCRIPTION/ORDERING INFORMATION

- More Gate Options Available at www.ti.com/littlelogic
- ESD Performance Tested Per JESD 22
 - 2000-V Human-Body Model (A114-B, Class II)
 - 1000-V Charged-Device Model (C101)



The SN74AUP1T157 is a single 2-input multiplexer that selects data from two data inputs (A and B) under control of a common data select input (C). The state of the common data select input determines the particular register from which the data comes. The output (Y) presents the selected data in the true (non-inverted) form.

AUP technology is the industry's lowest-power logic technology designed for use in extending battery-life in operating. All input levels that accept 1.8-V LVCMOS signals, while operating from either a single 3.3-V or 2.5-V V_{CC} supply. This product also maintains excellent signal integrity (see Figure 2 and Figure 3).

The wide V_{CC} range of 2.3 V to 3.6 V allows the possibility of switching output level to connect to external controllers or processors.

Schmitt-trigger inputs ($\Delta V_T = 210 \text{ mV}$ between positive and negative input transitions) offer improved noise immunity during switching transitions, which is especially useful on analog mixed-mode designs. Schmitt-trigger inputs reject input noise, ensure integrity of output signals, and allow for slow input signal transition.

 I_{off} is a feature that allows for powered-down conditions ($V_{CC} = 0$ V) and is important in portable and mobile applications. When $V_{CC} = 0$ V, signals in the range from 0 V to 3.6 V can be applied to the inputs and outputs of the device. No damage occurs to the device under these conditions.

The SN74AUP1T157 is designed with optimized current-drive capability of 4 mA to reduce line reflections, overshoot, and undershoot caused by high-drive outputs.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SN74AUP1T157



www.ti.com

SCES807 - APRIL 2010

ORDERING INFORMATION⁽¹⁾

T _A	PACKAGE ⁽²⁾		PACKAGE ⁽²⁾ ORDERABLE PART NUMBER		TOP-SIDE MARKING ⁽³⁾
40°C to 95°C		Reel of 3000	SN74AUP1T157DCKR	CI.	
–40°C to 85°C	SOT (SC-70) – DCK	Reel of 250	SN74AUP1T157DCKT	6L_	

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

(3) The actual top-side marking has one additional character that designates the wafer fab/assembly site.

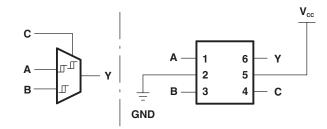


Figure 1. 2-to-1 Data Selector/Multiplexer When C is L, Y = B When C is H, Y = A

FUNCTION TABLE

	INPUTS (Lower Level Input)		OUTPUT (V _{CC} CMOS)
Α	В	С	Y
Х	L	L	L
Х	Н	L	Н
L	Х	Н	L
Н	Х	Н	Н

Supply $V_{CC} = 2.3 \text{ V}$ to 2.7 V (2.5 V)

V _{T+} max V _{T-} min =	OUTPUT CMOS			
Α	A B			
V _{IH} =	V _{IH} = 1.1 V			
$V_{IL} = 0$	0.35 V	$V_{OL} = 0.45 V$		

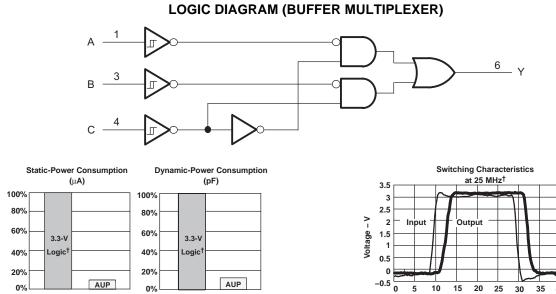
Supply $V_{CC} = 3 V$ to 3.6 V (3.3 V)

INP V _{T+} max = V _{T-} min =	OUTPUT CMOS			
Α	Y			
V _{IH} =	V _{IH} = 1.19 V			
V _{IL} =	0.5 V	$V_{OL} = 0.45 V$		



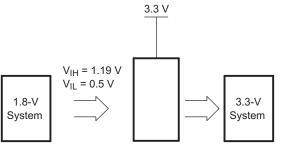
SN74AUP1T157

SCES807 - APRIL 2010



† Single, dual, and triple gates





2.5 V

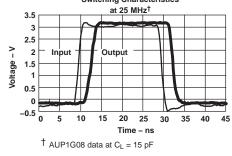
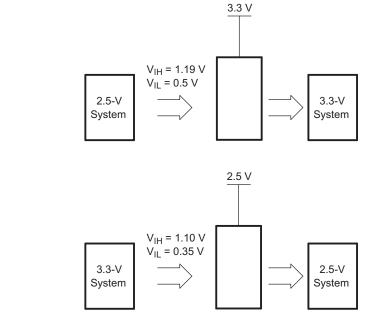


Figure 3. Excellent Signal Integrity





2.5-V

System

V_{IH} = 1.10 V

V_{IL} = 0.35 V

1.8-V

System

SN74AUP1T157

SCES807 - APRIL 2010



www.ti.com

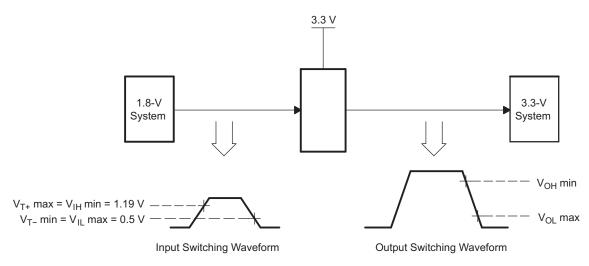


Figure 5. Switching Thresholds for 1.8-V to 3.3-V Translation



SCES807-APRIL 2010

www.ti.com

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		-0.5	4.6	V
VI	Input voltage range ⁽²⁾		-0.5	4.6	V
Vo	Voltage range applied to any output in the high-impedance or powe	r-off state ⁽²⁾	-0.5	4.6	V
Vo	Output voltage range in the high or low state ⁽²⁾	-0.5	V _{CC} + 0.5	V	
I _{IK}	Input clamp current	V ₁ < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
lo	Continuous output current			±20	mA
	Continuous current through V _{CC} or GND			±50	mA
θ_{JA}	Package thermal impedance ⁽³⁾	DCK package		259	°C/W
T _{stg}	Storage temperature range	-65	150	°C	

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2.3	3.6	V
VI	/I Input voltage				V
Vo	Output voltage		0	V_{CC}	V
	Lich lovel output ourrest	$V_{CC} = 2.3 V$		-3.1	~ ^
I _{OH}	High-level output current	$V_{CC} = 3 V$		-4	mA
		$V_{CC} = 2.3 V$		3.1	mA
IOL	Low-level output current	$V_{CC} = 3 V$		4	IIIA
T _A	Operating free-air temperature		-40	85	°C

 All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. See the TI application report *Implications* of Slow or Floating CMOS Inputs, literature number SCBA004.

TEXAS INSTRUMENTS

www.ti.com

SCES807 - APRIL 2010

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{cc}	T _A =	= 25°C	T _A = -40° to 85°C	°C	UNIT
			MIN	TYP MAX	MIN	MAX	
V _{T+}		2.3 V to 2.7 V	0.6	1.1	0.6	1.1	
Positive-going input threshold voltage		3 V to 3.6 V	0.75	1.16	0.75	1.19	V
V _{T-}		2.3 V to 2.7 V	0.35	0.6	0.35	0.6	
Negative-going input threshold voltage		3 V to 3.6 V	0.5	0.85	0.5	0.85	V
ΔV_T		2.3 V to 2.7 V	0.23	0.6	0.1	0.6	
Hysteresis (V _{T+} – V _{T–})		3 V to 3.6 V	0.25	0.56	0.15	0.56	V
	I _{OH} = -20 μA	2.3 V to 3.6 V	V _{CC} - 0.1		V _{CC} - 0.1		
	I _{OH} = -2.3 mA	2.3 V	2.05		1.97		
V _{OH}	I _{OH} = -3.1 mA	2.3 V	1.9		1.85		V
	$I_{OH} = -2.7 \text{ mA}$	3 V	2.72		2.67		
	$I_{OH} = -4 \text{ mA}$	3 V	2.6		2.55		
	I _{OL} = 20 μA	2.3 V to 3.6 V		0.1		0.1	
	I _{OL} = 2.3 mA	2.3 V		0.31		0.33	
V _{OL}	I _{OL} = 3.1 mA	2.3 V		0.44		0.45	V
	I _{OL} = 2.7 mA	3 V		0.31		0.33	
	$I_{OL} = 4 \text{ mA}$	3 V		0.44		0.45	
II All inputs	$V_1 = 3.6 V \text{ or GND}$	0 V to 3.6 V		0.1		0.5	μΑ
l _{off}	$V_1 \text{ or } V_0 = 0 \text{ V to } 3.6 \text{ V}$	0 V		0.1		0.5	μΑ
ΔI _{off}	$V_{1} \text{ or } V_{O} = 3.6 \text{ V}$	0 V to 0.2 V		0.2		0.5	μΑ
I _{CC}	$V_{I} = 3.6 \text{ V or GND}, I_{O} = 0$	2.3 V to 3.6 V		0.5		0.9	μΑ
	One input at 0.3 V or 1.1 V, Other inputs at 0 or V _{CC} , $I_0 = 0$	2.3 V to 2.7 V				4	μA
ΔI _{CC}	One input at 0.45 V or 1.2 V, Other inputs at 0 or V _{CC} , $I_0 = 0$	3 V to 3.6 V				12	μΑ
Ci	$V_{I} = V_{CC}$ or GND	3.3 V		1.5			pF
Co	$V_{O} = V_{CC}$ or GND	3.3 V		3			pF

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$, $V_I = 1.8 \text{ V} \pm 0.15 \text{ V}$ (unless otherwise noted) (see Figure 6)

	PARAMETER	FROM (INPUT)		C.		ק = 25°C	;	T _A = to 85	40°C 5°C	UNIT
			(OUTPUT)		MIN	TYP	MAX	MIN	MAX	
				5 pF	1.8	2.3	2.9	0.5	6.8	
			v	10 pF	2.3	2.8	3.4	1	7.9	
	t _{pd}	A, B, or C	Y	15 pF	2.6	3.1	3.8	1	8.7	ns
				30 pF	3.8	4.4	5.1	1.5	10.8	



SCES807-APRIL 2010

www.ti.com

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$, $V_1 = 2.5 \text{ V} \pm 0.2 \text{ V}$ (unless otherwise noted) (see Figure 6)

PARAMETER	FROM	TO			∖ = 25°C	;	T _A = to 85	40°C 5°C	UNIT
	(INPUT)	(OUTPUT)		MIN	TYP	MAX	MIN	MAX	
t _{pd}			5 pF	1.8	2.3	3.1	0.5	6	5
		v	10 pF	2.2	2.8	3.5	1	7.1	20
	A, B, or C	ř	15 pF	2.6	3.2	5.2	1	7.9	ns
			30 pF	3.7	4.4	5.2	1.5	10	

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$, $V_I = 3.3 \text{ V} \pm 0.3 \text{ V}$ (unless otherwise noted) (see Figure 6)

PARAMETER	FROM	TO (OUTPUT)	CL	т,	₄ = 25°C		T _A = to 85	40°C 5°C	UNIT
	(INPUT)			MIN	TYP	MAX	MIN	MAX	
t _{pd}			5 pF	2	2.7	3.5	0.5	5.5	
		v	10 pF	2.4	3.1	3.9	1	6.5	
	A, B, or C	Y	15 pF	2.8	3.5	4.3	1	7.4	ns
			30 pF	4	4.7	5.5	1.5	9.5	

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$, $V_I = 1.8 \text{ V} \pm 0.15 \text{ V}$ (unless otherwise noted) (see Figure 6)

PARAMETER	PARAMETER	FROM	TO			₄ = 25°C		T _A = to 85	40°C 5°C	UNIT
	(INPUT)	(OUTPUT)		MIN	TYP	MAX	MIN	MAX		
t _{pd}			5 pF	1.6	2	2.5	0.5	8		
		v	10 pF	2	2.4	2.9	1	8.5	~~	
	A, B, or C	Ť	15 pF	2.3	2.8	3.3	1	9.1	ns	
			30 pF	3.4	3.9	4.4	1.5	9.8		

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$, $V_1 = 2.5 \text{ V} \pm 0.2 \text{ V}$ (unless otherwise noted) (see Figure 6)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _L T _A = 25°C				T _A = to 85	40°C 5°C	UNIT
		(001201)		MIN	TYP	MAX	MIN	MAX	
		v	5 pF	1.6	1.9	2.4	0.5	5.3	
			10 pF	2	2.3	2.7	1	6.1	
۲pd	A, B, or C	ř	15 pF	2.3	2.7	3.1	1	6.8	ns
			30 pF	3.4	3.8	4.2	1.5	8.5	



SCES807 - APRIL 2010

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$, $V_I = 3.3 \text{ V} \pm 0.3 \text{ V}$ (unless otherwise noted) (see Figure 6)

PARAMETER	FROM	TO	CL	т,	₄ = 25°C		T _A = to 85	UNIT		
	(INPUT)	(OUTPUT)		MIN	TYP	MAX	MIN	MAX		
t _{pd}	A, B, or C	Y	5 pF	1.6	2.1	2.7	0.5	4.7	7	
			10 pF	2	2.4	3	1	5.7		
			T	15 pF	2.3	2.7	3.3	1	6.2	ns
			30 pF	3.4	3.8	4.4	1.5	7.8		

OPERATING CHARACTERISTICS

 $T_A = 25^{\circ}C$

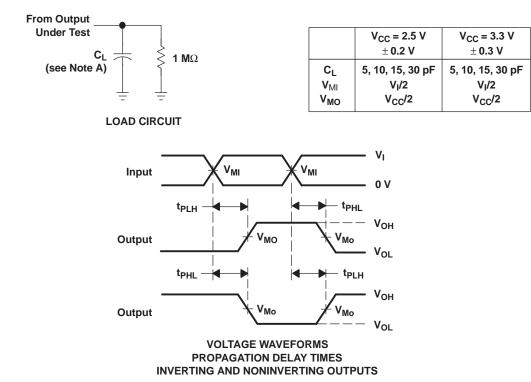
	PARAMETER	TEST CONDITIONS	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	UNIT
C_{pd}	Power dissipation capacitance	f = 10 MHz	4	5	pF

SN74AUP1T157

TEXAS INSTRUMENTS

www.ti.com

SCES807-APRIL 2010



PARAMETER MEASUREMENT INFORMATION

- NOTES: A. C_L includes probe and jig capacitance.
 - B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , slew rate \geq 1 V/ns.
 - C. The outputs are measured one at a time, with one transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 6. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing		ickage Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AUP1T157DCKR	ACTIVE	SC70	DCK	6 3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

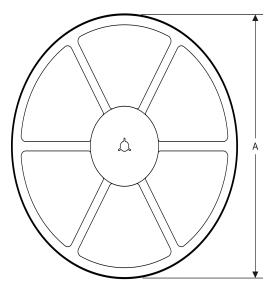
PACKAGE MATERIALS INFORMATION

www.ti.com

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TEXAS INSTRUMENTS





TAPE AND REEL INFORMATION

TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUP1T157DCKR	SC70	DCK	6	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74AUP1T157DCKR	SC70	DCK	6	3000	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3

TEXAS INSTRUMENTS

www.ti.com

PACKAGE MATERIALS INFORMATION

9-May-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUP1T157DCKR	SC70	DCK	6	3000	180.0	180.0	18.0
SN74AUP1T157DCKR	SC70	DCK	6	3000	338.0	343.0	30.0

DCK (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-203 variation AB.



LAND PATTERN DATA



NOTES:

- A. All linear dimensions are in millimeters.B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Mobile Processors	www.ti.com/omap		
Wireless Connectivity	www.ti.com/wirelessconnectivity		
	TI 505 0		

TI E2E Community Home Page

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2012, Texas Instruments Incorporated